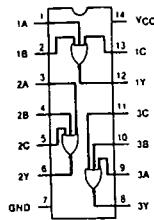


Technical Data

CD54/74HC27**CD54/74HCT27****High-Speed CMOS Logic****FUNCTIONAL DIAGRAM AND TERMINAL ASSIGNMENT**

The RCA-CD54/74HC27 and CD54/74HCT27 logic gates utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL gates with the low power consumption of standard CMOS integrated circuits. All devices have the ability to drive 10 LSTTL loads. The CD54/74HCT logic family is functionally as well as pin compatible with the standard 54LS/74LS logic family.

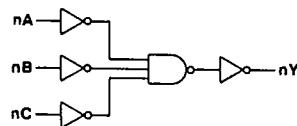
The CD54HC27 and CD54HCT27 are supplied in 14-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC27 and CD74HCT27 are supplied in 14-lead dual-in-line plastic packages (E suffix) and in 14-lead dual-in-line surface mount plastic packages (M suffix). Both types are also available in chip form (H suffix).

Triple 3-Input NOR Gate**Type Features:**

- *Buffered Inputs*
- *Typical CD54/74HC27 Propagation Delay = 7ns
@ V_{cc} = 5v, C_L = 15pF, T_A = 25° C*

Family Features:

- *Fanout (Over Temperature Range):
Standard Outputs - 10 LSTTL Loads
Bus Driver Outputs - 15 LSTTL Loads*
- *Wide Operating Temperature Range:
CD74HC/HCT: -40 to +85° C*
- *Balanced Propagation Delay and Transition Times*
- *Significant Power Reduction Compared to LSTTL Logic ICs*
- *Alternate Source Is Philips/Signetics*
- **CD54HC/CD74HC Types:**
2 to 6 V Operation
High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{cc}, @ V_{cc} = 5 V
- **CD54HCT/CD74HCT Types:**
4.5 to 5.5 V Operation
Direct LSTTL Input Logic Compatibility
V_{IL} = 0.8 V Max., V_{IH} = 2 V Min.
CMOS Input Compatibility
I_I ≤ 1 μA @ V_{OL}, V_{OH}



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LOGIC DIAGRAM**TRUTH TABLE**

nA	nB	nC	nY
L	L	L	H
L	L	H	L
L	H	L	L
H	L	L	L
H	H	L	L
L	H	H	L
H	L	H	L
H	H	H	L

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L = Low Level
H = High Level

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MAXIMUM RATINGS, Absolute-Maximum Values:DC SUPPLY-VOLTAGE, (V_{cc}):

(Voltages referenced to ground)	-0.5 to +7 V
DC INPUT DIODE CURRENT, I_{ix} (FOR $V_i < -0.5$ V OR $V_i > V_{cc} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{ox} (FOR $V_o < -0.5$ V OR $V_o > V_{cc} + 0.5$ V)	± 20 mA
DC DRAIN CURRENT, PER OUTPUT (I_o) (FOR -0.5 V < $V_o < V_{cc} + 0.5$ V)	± 25 mA
DC V_{cc} OR GROUND CURRENT (I_{cc})	± 50 mA

POWER DISSIPATION PER PACKAGE (P_o):

For $T_A = -40$ to $+60^\circ C$ (PACKAGE TYPE E)	500 mW
For $T_A = +60$ to $+85^\circ C$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ C$ to 300 mW
For $T_A = -55$ to $+100^\circ C$ (PACKAGE TYPE F, H)	500 mW
For $T_A = +100$ to $+125^\circ C$ (PACKAGE TYPE F, H)	Derate Linearly at 8 mW/ $^\circ C$ to 300 mW
For $T_A = -40$ to $+70^\circ C$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ C$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ C$ to 70 mW

OPERATING-TEMPERATURE RANGE (T_A):

PACKAGE TYPE F, H	-55 to $+125^\circ C$
PACKAGE TYPE E, M	-40 to $+85^\circ C$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ C$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s max.	$+265^\circ C$
Unit inserted into a PC Board (min. thickness $1/16$ in., 1.59 mm) with solder contacting lead tips only	$+300^\circ C$

**RECOMMENDED OPERATING CONDITIONS:**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For $T_A = \text{Full Package-Temperature Range}$) V_{cc} :*			
CD54/74HC Types	2	6	V
CD54/74HCT Types	4.5	5.5	
DC Input or Output Voltage V_i , V_o	0	V_{cc}	V
Operating Temperature T_A :			
CD74 Types	-40	$+85$	$^\circ C$
CD54 Types	-55	$+125$	
Input Rise and Fall Times t_r , t_f			
at 2 V	0	1000	
at 4.5 V	0	500	ns
at 6 V	0	400	

*Unless otherwise specified, all voltages are referenced to Ground.

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CD74HC27/CDS4HC27								CD74HCT27/CDS4HCT27								UNITS						
	TEST CONDITIONS			74HC/54HC TYPES		74HC TYPE		54HC TYPE		TEST CONDITIONS			74HCT/54HCT TYPES		74HCT TYPE		54HCT TYPE						
	V _I V	I _O mA	V _{CC} V	+25°C			-40/ +85°C		-55/ +125°C		V _I V	V _{CC} V	+25°C			-40/ +85°C		-55/ +125°C					
High-Level Input Voltage V _{IN}				2	1.5	—	—	1.5	—	1.5	—		4.5	—	—	—	—	—	V				
				4.5	3.15	—	—	3.15	—	3.15	—		5.5	—	—	2	—	2	V				
				6	4.2	—	—	4.2	—	4.2	—		—	—	—	—	—	—	V				
Low-Level Input Voltage V _{IL}				2	—	—	0.5	—	0.5	—	0.5	—	V _{IL} or V _{IH}	4.5	—	—	—	—	—	V			
				4.5	—	—	1.35	—	1.35	—	1.35	—		5.5	—	—	0.8	—	0.8	V			
				6	—	—	1.8	—	1.8	—	1.8	—		—	—	—	—	—	—	V			
High-Level Output Voltage V _{OH} or CMOS Loads	V _{IL} or V _{OH}	-0.02	2	1.9	—	—	1.9	—	1.9	—	V _{IL} or V _{IH}	—	—	—	—	—	—	—	V				
			4.5	4.4	—	—	4.4	—	4.4	—		4.5	4.4	—	—	4.4	—	4.4	—	V			
			6	5.9	—	—	5.9	—	5.9	—		—	—	—	—	—	—	—	—	V			
TTL Loads	V _{IL} or V _{IL}	—4	4.5	3.98	—	—	3.84	—	3.7	—	V _{IL} or V _{IL}	—	—	—	—	3.84	—	3.7	—	V			
			-4	4.5	3.98	—	—	3.84	—	3.7	—	4.5	3.98	—	—	3.84	—	3.7	—	V			
			5.2	6	5.48	—	—	5.34	—	5.2	—	—	—	—	—	—	—	—	V				
Low-Level Output Voltage V _{OL} or CMOS Loads	V _{IL} or V _{OL}	0.02	2	—	—	0.1	—	0.1	—	0.1	—	V _{IL} or V _{IL}	—	—	—	—	0.1	—	0.1	—	V		
			4.5	—	—	0.1	—	0.1	—	0.1	—		4.5	—	—	0.1	—	0.1	—	V			
			6	—	—	0.1	—	0.1	—	0.1	—		—	—	—	—	—	—	—	V			
TTL Loads	V _{IL} or V _{IL}	4	4.5	—	—	0.26	—	0.33	—	0.4	—	V _{IL} or V _{IL}	—	—	—	—	0.26	—	0.33	—	V		
			5.2	6	—	—	0.26	—	0.33	—	0.4	—	4.5	—	—	0.26	—	0.33	—	V			
			—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	V				
Input Leakage Current I _L	V _{CC} or Gnd	6	—	—	±0.1	—	±1	—	±1	—	Any Voltage Between V _{CC} & Gnd	5.5	—	—	±0.1	—	±1	—	±1	—	μA		
Quiescent Device Current I _{CC}	V _{CC} or Gnd	0	6	—	—	2	—	20	—	40	V _{CC}	5.5	—	—	2	—	20	—	40	μA			
Additional Quiescent Device Current per input pin. 1 unit load ΔI _{CC} *											V _{CC} -2.1	4.5	to	—	100	360	—	450	—	490	μA		

*For dual-supply systems theoretical worst case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.

HCT Input Loading Table

Input	Unit Loads*
All	1.5

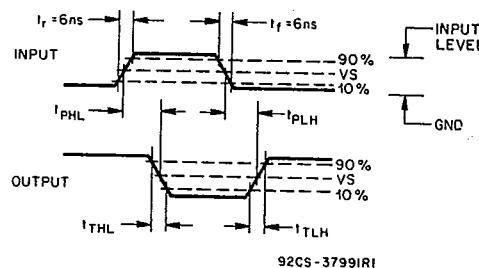
*Unit Load is ΔI_{CC} limit specified in Static Characteristic Chart, e.g., 360 μA max. @ 25°C.

CD54/74HC27
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SWITCHING CHARACTERISTICS ($V_{cc} = 5$ V, $T_A = 25^\circ C$, Input $t_o, t_i = 6$ ns)

CHARACTERISTIC	C_L (pF)	SYMBOL	TYPICAL		UNITS
			HC	HCT	
Propagation Delay, Data Input to Output Y (Fig. 1)	15	t_{PLH} t_{PHL}	7	9	ns
Power Dissipation Capacitance*	—	C_{PD}	26	28	pF

* C_{PD} is used to determine the dynamic power consumption, per gate. $PD = V_{cc} \cdot I_i \cdot (C_{PD} + C_L)$ I_i = input frequency C_L = output load capacitance V_{cc} = supply voltageSWITCHING CHARACTERISTICS ($C_L = 50$ pF, Input $t_o, t_i = 6$ ns)

CHARACTERISTIC	SYMBOL	V_{cc}	25°C				-40°C to +85°C				-55°C to +125°C				UNITS	
			HC		HCT		74HC		74HCT		54HC		54HCT			
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Propagation Delay, Input to Output (Fig. 1)	t_{PLH}	2	95	—	—	—	120	—	—	145	—	—	—	—	ns	
	t_{PHL}	4.5	19	23	—	—	24	29	—	29	35	35	—	—	ns	
		6	16	—	—	20	—	—	—	25	—	—	—	—	ns	
Transition Times (Fig. 1)	t_{TLH}	2	75	—	—	—	95	—	—	110	—	—	—	—	ns	
	t_{THL}	4.5	15	15	15	19	19	19	19	22	22	—	—	—	ns	
		6	13	—	—	16	—	—	—	19	—	—	—	—	ns	
Input Capacitance	C_I	—	10	—	10	—	10	—	10	—	10	—	10	—	pF	



	54/74HC	54/74HCT
Input Level	V_{cc}	3V
Switching Voltage, V_s	50% V_{cc}	1.3 V

Fig. 1 - Transition times and propagation delay times.